

INTEGRATED CIRCUIT CHIP PACKAGE

Abstract of the Disclosure

5 A package for an integrated circuit chip adapted to
operate at microwave frequencies. The package includes an
electrically conductive lead frame having electrical leads
extending outwardly from an inner region. A base section is
adhesively affixed to a bottom portion of the lead frame:
The base section and a plastic cover are configured to
provide a cavity when the cover and the base section are
affixed with the integrated circuit chip being disposed with
such provided cavity. With another integrated circuit chip
10 package, an electrically conductive lead frame has
electrical leads adapted for electrical connection to the
integrated circuit chip. The base section includes a
conductive member and a dielectric member. The dielectric
member has an aperture disposed in registration with an
15 inner region of the lead frame. The conductive member is
electrically to a bottom surface portion of the integrated
circuit. The integrated circuit chip being disposed in
registration with the aperture. A plastic cover and the
base section are configured to provide a cavity when the
20 cover and the bottom are affixed with the integrated circuit
chip being disposed with such provided cavity and with a
bottom surface portion of the conductive member being
exposed exteriorly of the package.

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